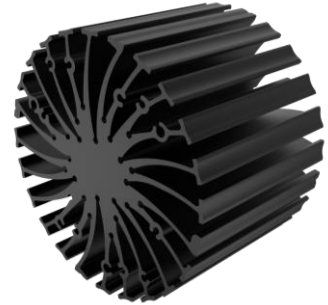


EtraLED

EtraLED-CRE-8550 CREE Modular Passive Star Heat Sink ϕ 85mm

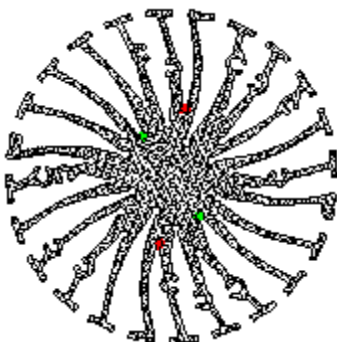
Features VS Benefits

- * The EtraLED-CRE-8550 Cree Modular Passive Star LED Heat Sinks are specifically designed for luminaires using the Cree LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1700 to 4,300 lumen.
- * Thermal resistance range R_{th} 1.72°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Cree® XLamp® COB series.
- * Diameter 85mm - standard height 50mm, Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Cree COB's and LED modules which standard fit on the srar LED heat sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.



Cree LED Modules directly Mounting Options

Cree® XLamp® COB Series:

- Xlamp CXA 13xx;
- Xlamp CXB 13xx;

With the Zhaga Book 11 holders for the green indicator marks.
 IDEAL Holder:50-2100CR;
 BJB Holder:47.319.6020.50;
 Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:
 Olivia series: FN14637-S; FN14828-M;
 Ronda series: FN15xxx-xx;

Cree® XLamp® COB Series:

- Xlamp CXA 18xx;
- Xlamp CXB 18xx;

With the Zhaga Book 3 holders for the green indicator marks.
 IDEAL Holder:50-2101CR;
 BJB Holder:47.319.2131.50;
 Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:
 Olivia series: FN14637-S; FN14828-M;
 Ronda series: FN15xxx-xx;

Cree® XLamp® COB Series:

- Xlamp CXA 15xx;
- Xlamp CXB 15xx;

With the Zhaga Book 11 holders for the red indicator marks.
 IDEAL Holder:50-2001CR;
 BJB Holder:47.319.6104.50;
 AAG.STUCCHI holder:8400-G2;
 Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:
 Ronda series: FN15xxx-xx;

EtraLED

EtraLED-CRE-8550 CREE Modular Passive Star Heat Sink Φ 85mm

Mounting Options and Drawings & Dimensions

Example: EtraLED-CRE-8550-B-1,2

Example: EtraLED-CRE-85 **1** - **2** - **3**

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

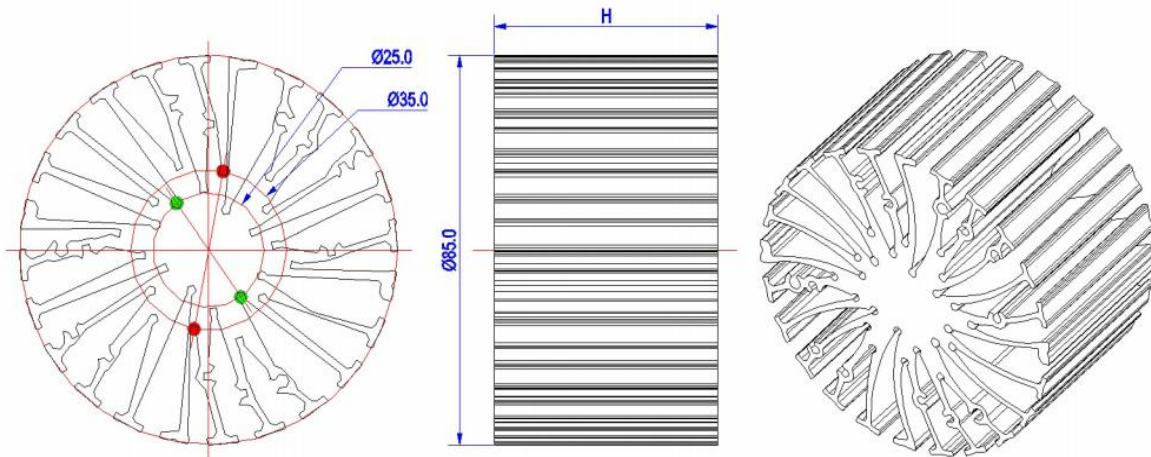
Ex.order code - 12

means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Olivia series	Ronda series			
1	Xlamp CXA 13xx; Xlamp CXB 13xx;	BJB Holder 47.319.6104.50	FN14637-S;		M3	6.5mm	25.0mm/ 2-@180° (Zhaga Book 11)
		IDEAL Holder 50-2001CR					
	Xlamp CXA 15xx; Xlamp CXB 15xx;	BJB Holder 47.319.6104.50	/				
		AAG.STUCCHI 8400-G2					
2	Xlamp CXA 18xx; Xlamp CXB 18xx;	BJB Holder 47.319.2131.50	FN14637-S; FN14828-M;		M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
		IDEAL Holder 50-2101CR					



EtraLED

EtraLED-CRE-8550 CREE Modular Passive Star Heat Sink Φ85mm

The product data table

	Model No.	EtraLED-CRE-8550
	Heatsink Size	Φ85xH50mm
	Heatsink Material	AL6063-T5
	Finish	Black Anodized
	Weight (g)	286.0
	Dissipated power (T_{hs-amb},50°C)	29.0 (W)
	Cooling surface area (mm²)	94366
	Thermal Resistance (R_{hs-amb})	1.72 (°C/W)

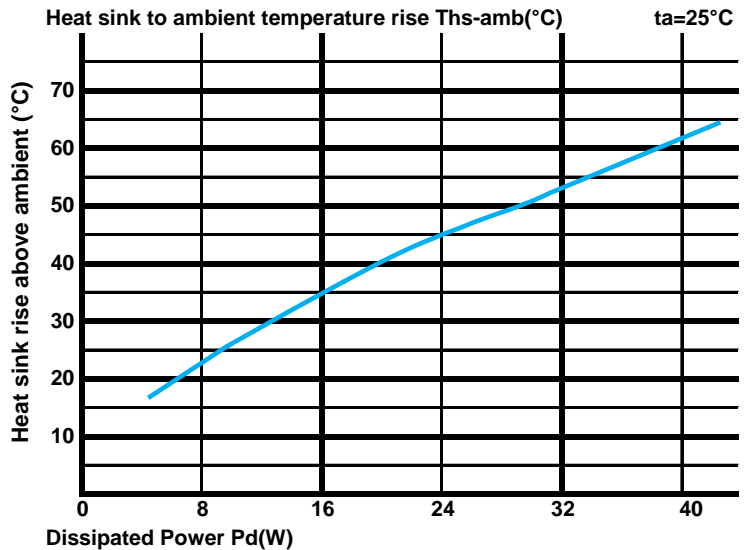
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

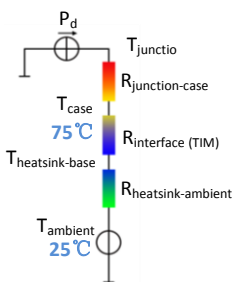
Dissipated Power Pd(W)	Pd = Pe x (1-ηL)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		EtraLED-CRE-8550	
8.0		2.88	23.0
16.0		2.19	35.0
24.0		1.88	45.0
32.0		1.66	53.0
40.0		1.53	61.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W]; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$